

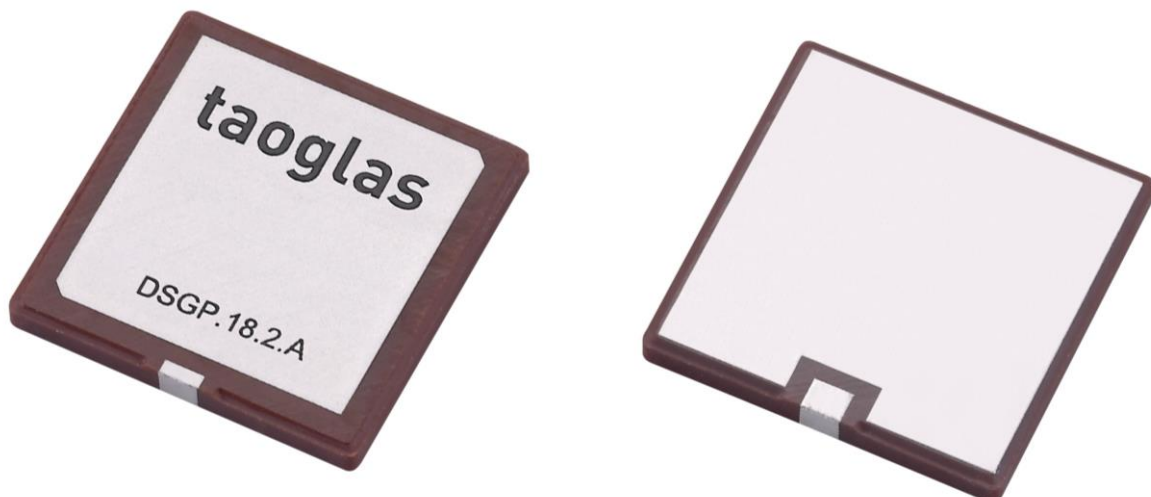


**THE DATASHEET OF  
SGP.1575.18.2.A.02**



## SPECIFICATION

- Part No. : **DSGP.1575.18.2.A.02**
- Description : GPS L1 / GALILEO E1 1575MHz 18\*18\*2mm  
Ceramic Patch SMT Antenna
- Features : 2.4 dBi Peak Gain for GPS/GALILEO Band  
Dimensions: 18 x 18 x 2mm  
SMT Direct Mount Ceramic Patch Antenna  
TS16949 Approved  
RoHS Compliant



## 1. Introduction

The DSGP.1575.18.2.A.02 is a ceramic GPS L1 / GALILEO E1 passive patch antenna, 18mm square, with a low profile of 2mm thickness. It is designed for applications in space constrained navigation devices, vehicle tracking/fleet management systems, as well as telematics devices.

The antenna has been tuned on a 50 x 50 mm ground plane, working at 1575.42MHz with a 2.4 dBi gain. The ceramic patch is mounted via SMT process, ideal for high volume low cost assembly. It is manufactured and tested in a TS16949 first tier automotive approved facility.

For further optimization to customer specific device environments where ground-plane size is different, custom tuned patch antennas can be supplied. For more details please contact your regional Taoglas sales office.

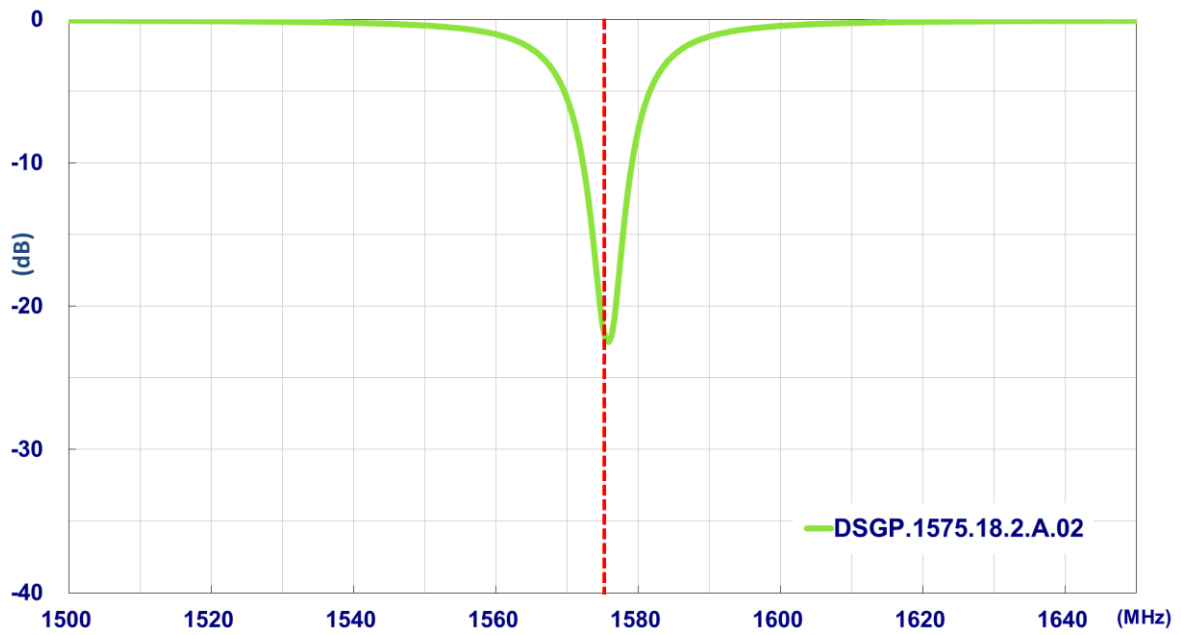
## 2. Specification

ELECTRICAL	
Application Bands	GPS/GALILEO
Operation Frequency (MHz)	1575.42 ±1.023
Return Loss (dB)	< -10
Gain at Zenith (dBi)	2.4
Efficiency (%)	55.94
Impedance	50 ohms
MECHANICAL	
Ceramic Dimension (mm)	18 x 18 x 2
Weight (g)	2.9
ENVIRONMENTAL	
Operation Temperature	-40°C to 85°C
Humidity	Non-condensing 65°C 95% RH

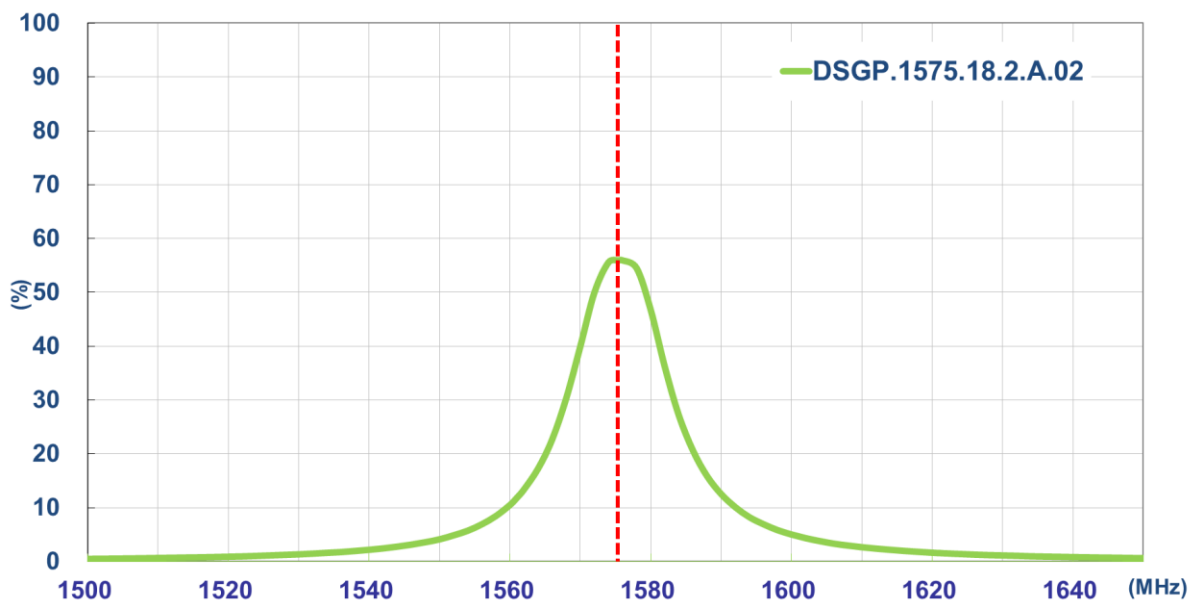
\* Antenna properties were measured with the antenna mounted on 50\*50mm Ground Plane  
Taoglas Part # DSGPD.18B

### 3. Antenna Characteristics

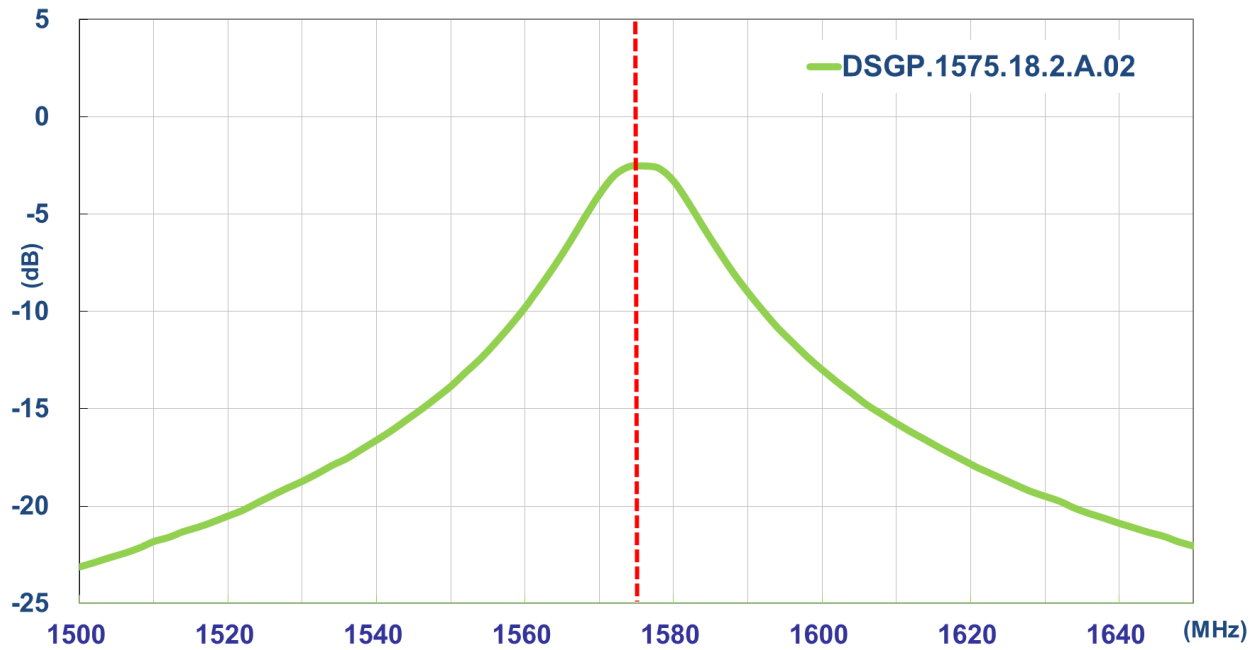
#### 3.1. Return Loss



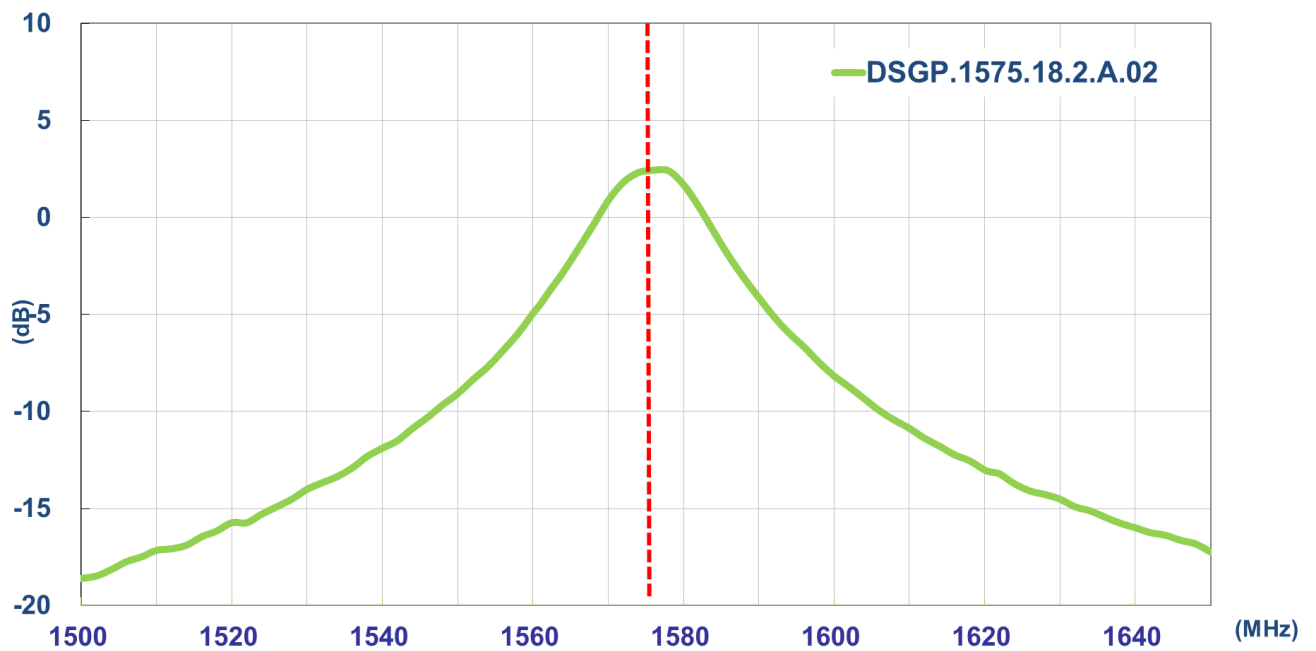
#### 3.2. Efficiency



### 3.3. Average Gain



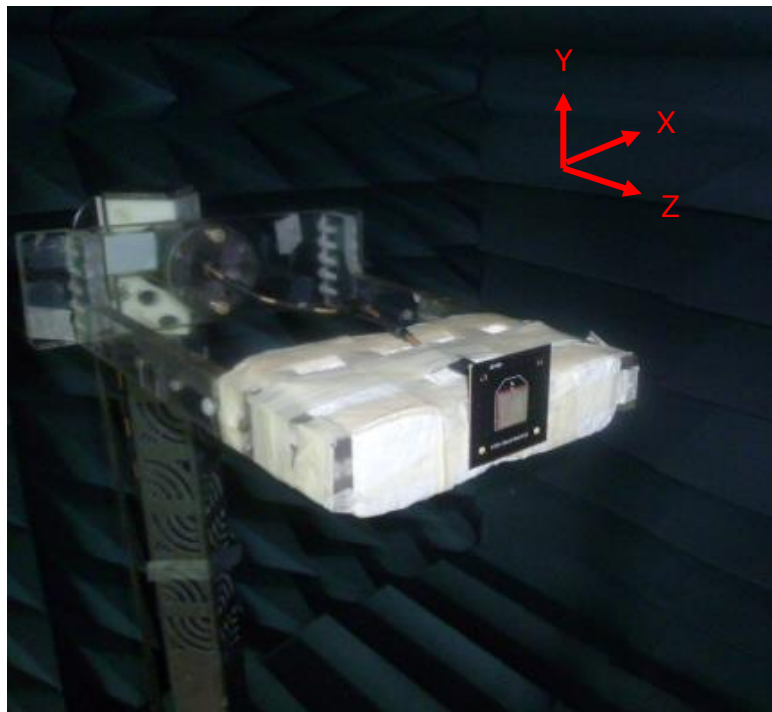
### 3.4. Peak Gain



## 4. Antenna Radiation Pattern

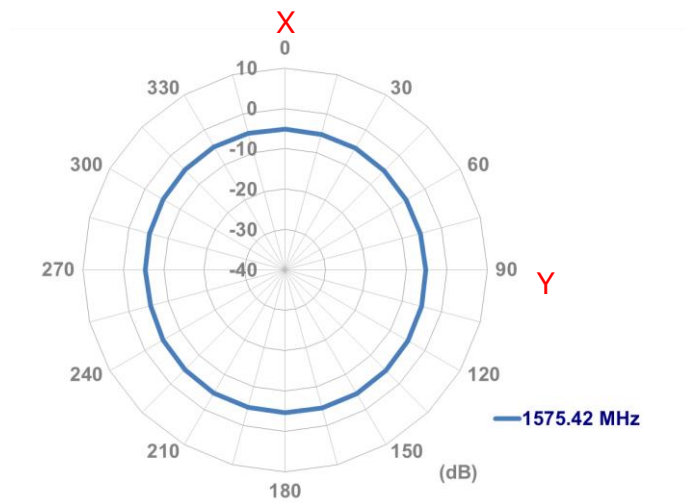
### 4.1. Measurement Setup

The DSGP.1575.18.2 antenna is tested with 50mm\*50mm ground plane in a CTIA certified ETS-Lindgren Anechoic Chamber. The test setup is shown below.

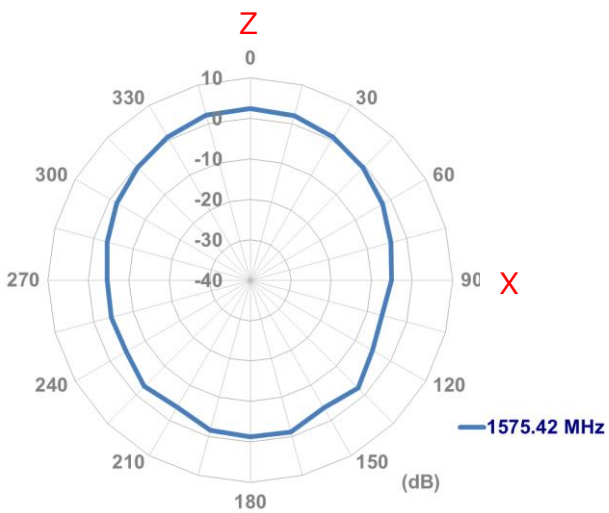


## 4.2. 2D Radiation Pattern

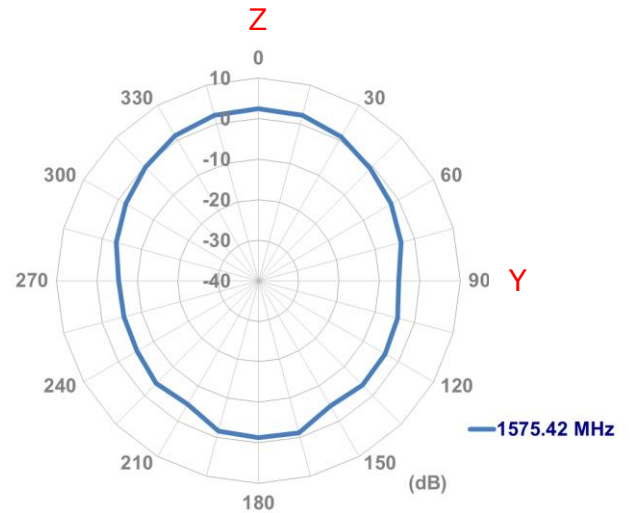
XY Plane



XZ Plane

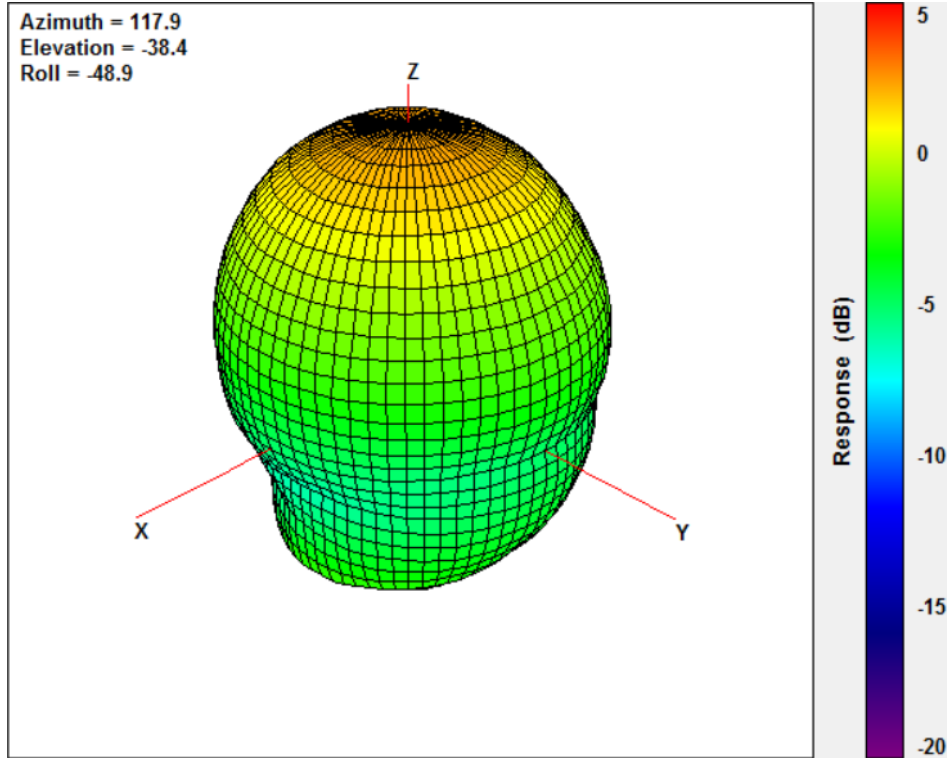


YZ Plane



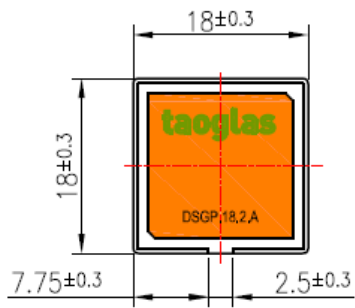
### 4.3. 3D Radiation Pattern

1575.42MHz

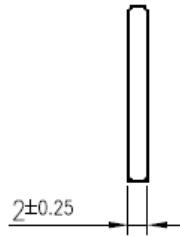


## 5. Mechanical Drawing (Unit: mm)

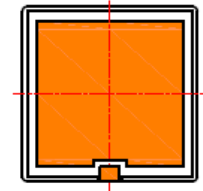
Top View



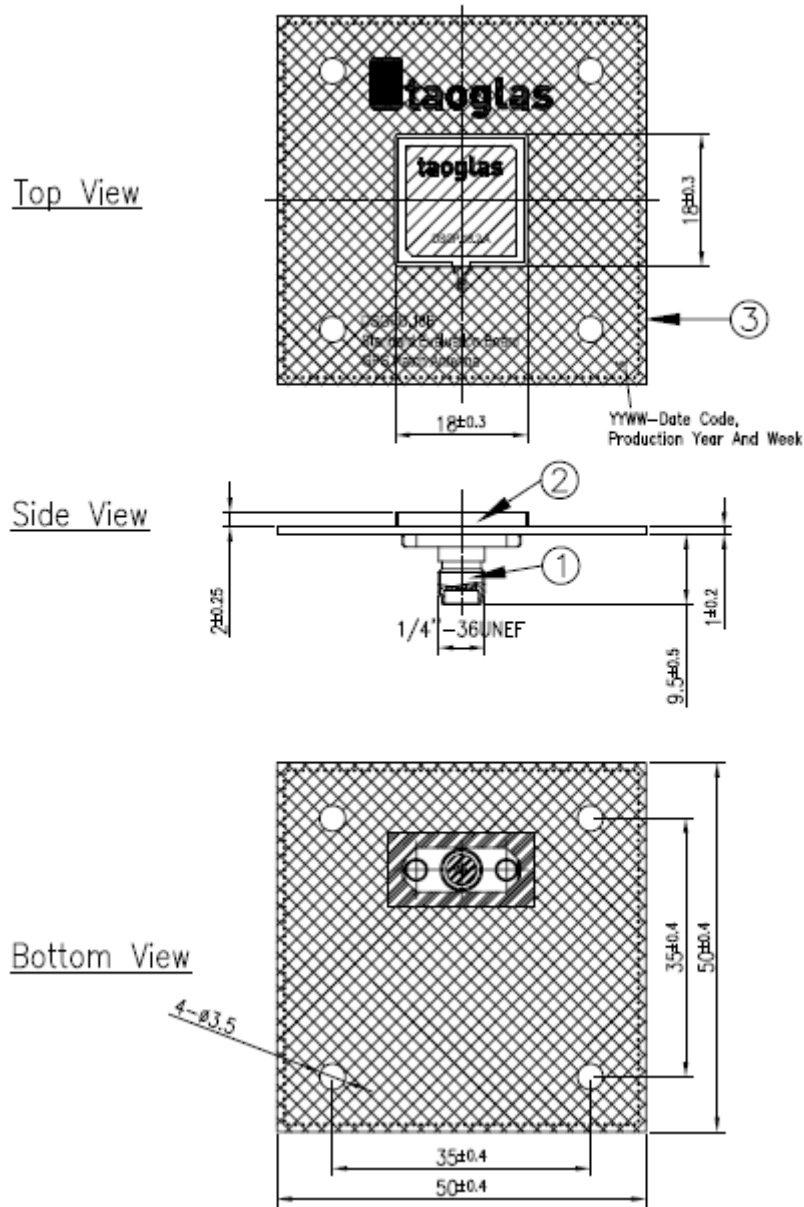
Side View



Bottom View

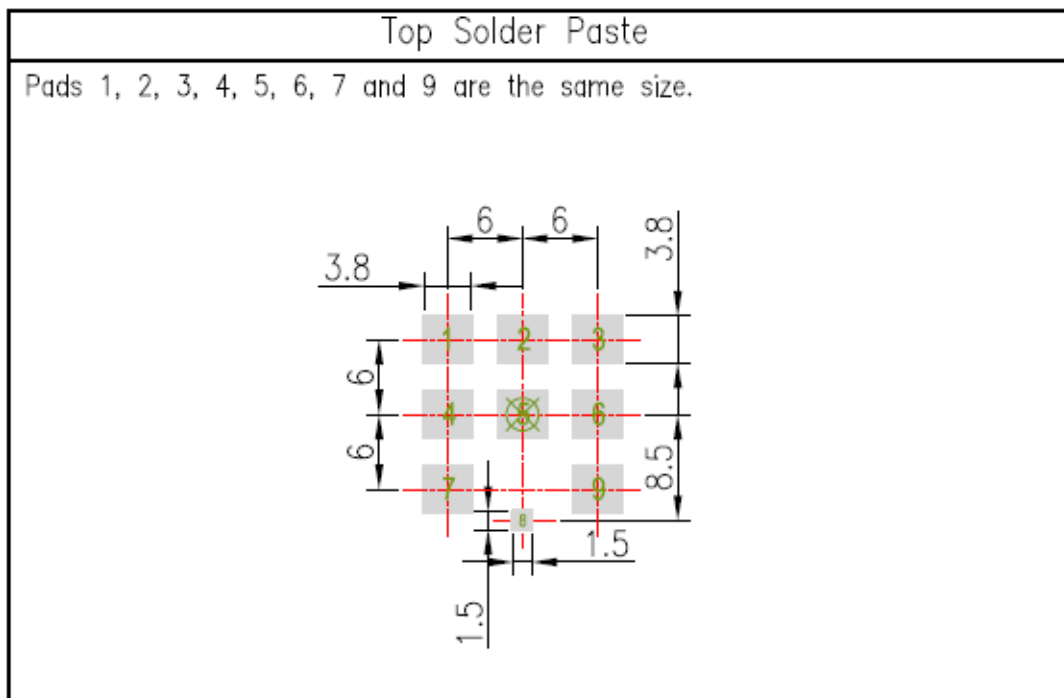
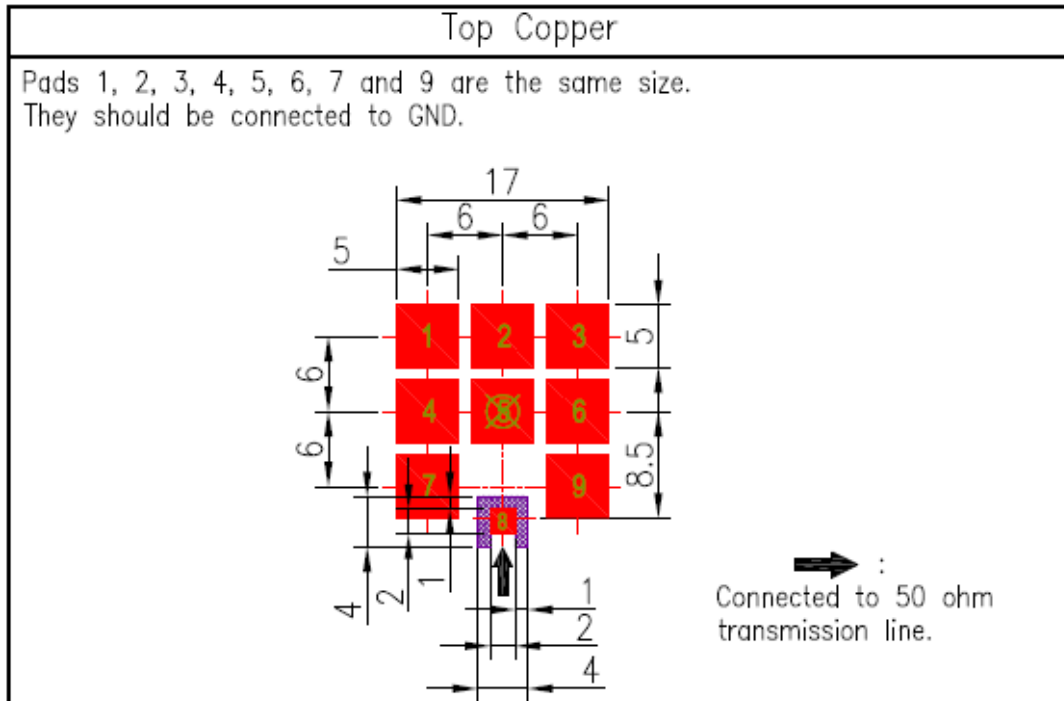


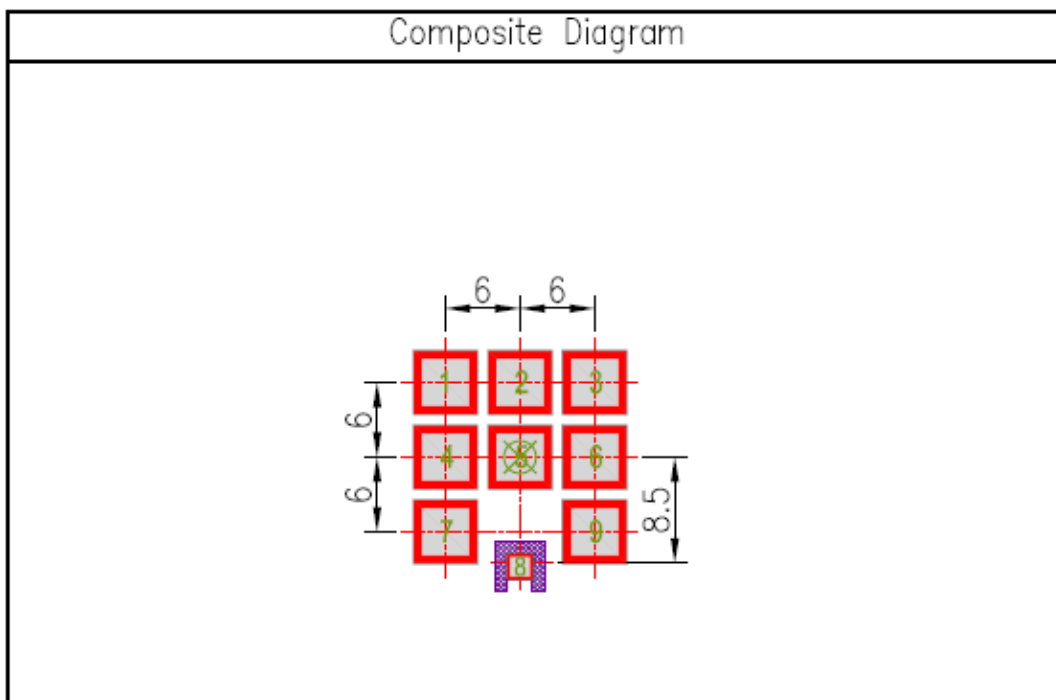
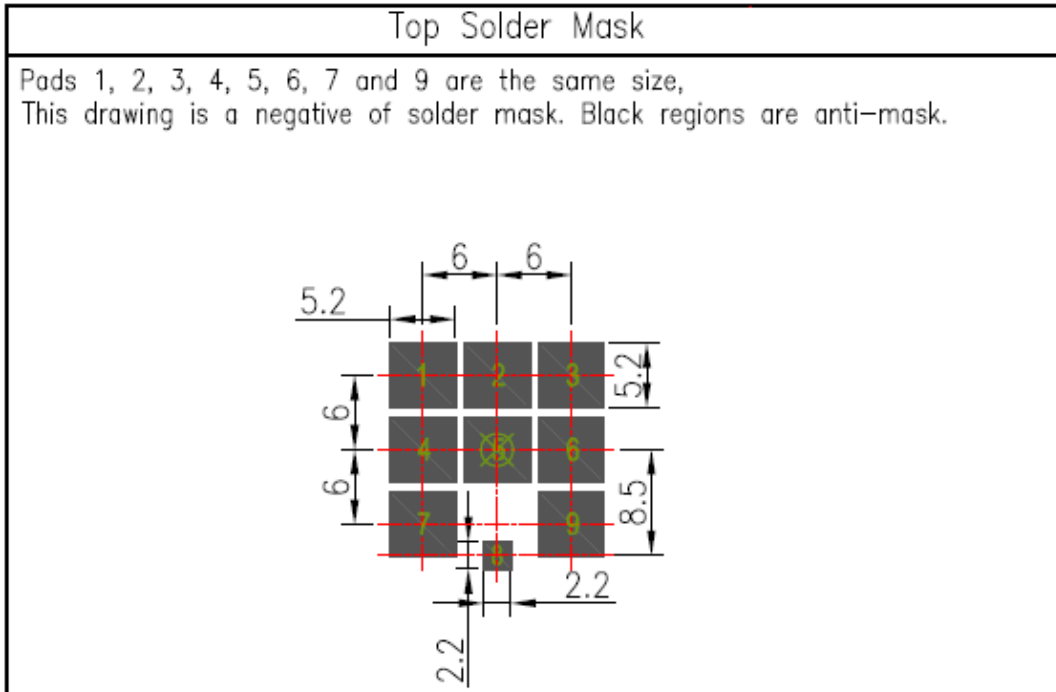
## 6. Evaluation Board (DSGPD.18B) (Unit: mm)



	Name	Material	Finish	QTY
1	PCB SMA(F) ST	Brass	Gold	1
2	DSGP.1575.18.2.A.02 Antenna	Ceramic	Clear	1
3	PCB (50x50x1mm)	Composite	Black	1

## 7. PCB Footprint Recommendation





unit :mm

NOTE:

- 1. Ag Plated area
- 2. Solder Mask area
- 3. Copper area
- 4. Paste area
- 5. Copper Keepout Area



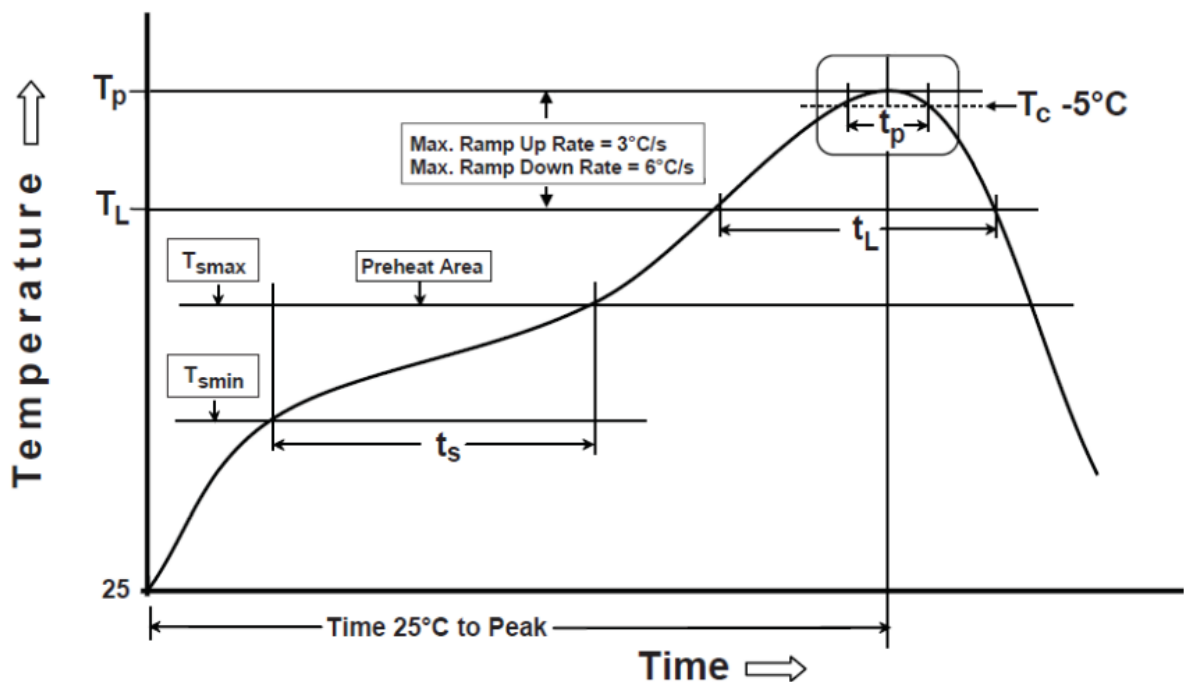
- 6. Copper keepout should extend through all PCB layers.
- 7. Any vias in pads should be either filled or tented to prevent solder from wicking away from the pad during reflow.
- 8. The dimension tolerances should follow standard PCB manufacturing guidelines

## 8. Recommended Reflow Soldering Profile

DSGP.1575.18 can be assembled following Pb-free assembly. According to the Standard IPC/JEDEC J-STD-020C, the temperature profile suggested is as follow:

Phase	Profile Features	Pb-Free Assembly (SnAgCu)
PREHEAT	Temperature Min( $T_{smin}$ )	150°C
	Temperature Max( $T_{smax}$ )	200°C
	Time( $t_s$ ) from ( $T_{smin}$ to $T_{smax}$ )	60-120 seconds
RAMP-UP	Avg. Ramp-up Rate ( $T_{smax}$ to $T_P$ )	3°C/second(max)
REFLOW	Temperature( $T_L$ )	217°C
	Total Time above $T_L$ ( $t_L$ )	30-100 seconds
PEAK	Temperature( $T_P$ )	260°C
	Time( $t_p$ )	2-5 seconds
RAMP-DOWN	Rate	3°C/second(max)
Time from 25°C to Peak Temperature		8 minutes max.
Composition of solder paste		96.5Sn/3Ag/0.5Cu
Solder Paste Model		SHENMAO PF606-P26

The graphic shows temperature profile for component assembly process in reflow ovens

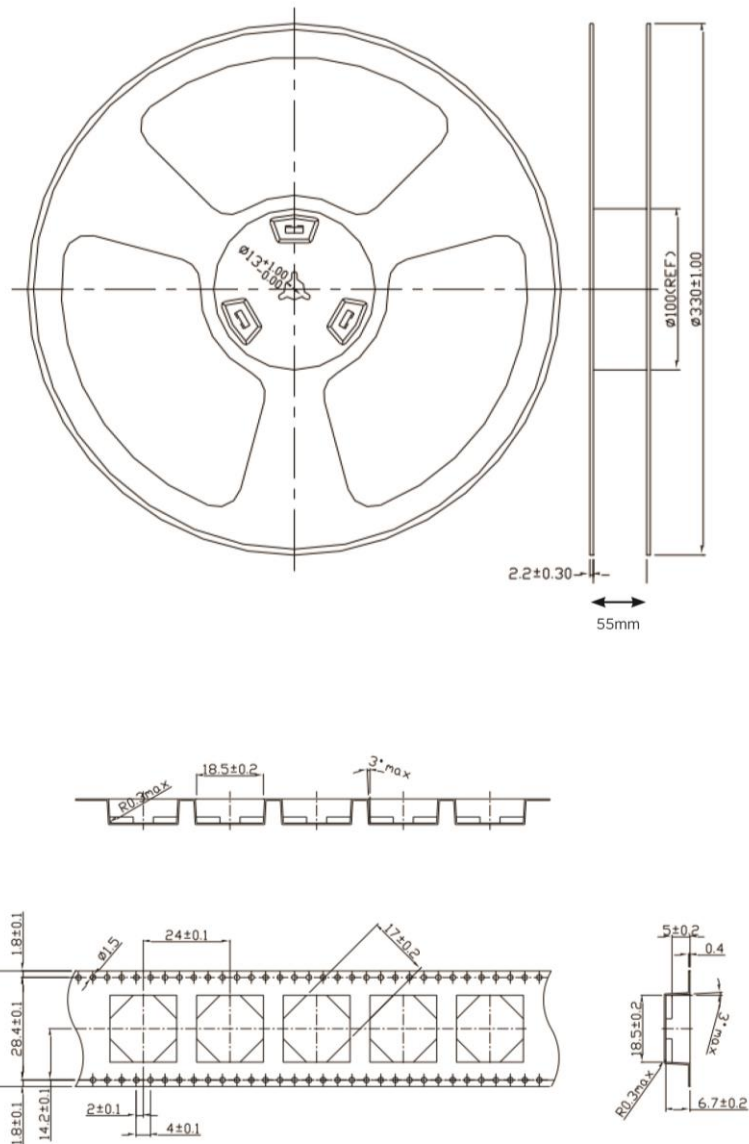


Soldering Iron condition : Soldering iron temperature 270°C±10°C.

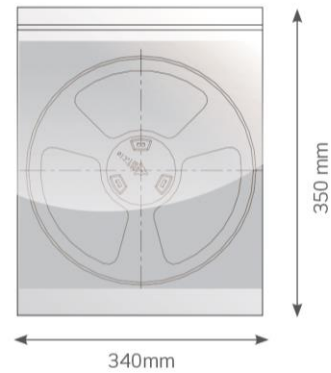
Apply preheating at 120°C for 2-3 minutes. Finish soldering for each terminal within 3 seconds, if soldering iron

## 9. Packaging

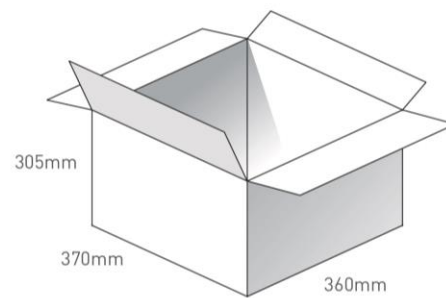
200 pc DSGP.1575.18.2.A.02 per reel  
 Dimensions -  $\varnothing 330 \times 55 \text{mm}$   
 Weight - 800g



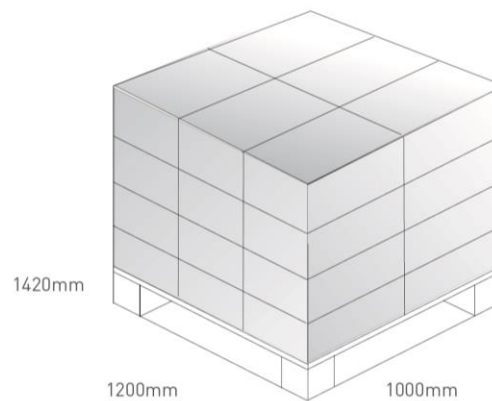
1 pc reel in small in Anti-static Bag  
Dimensions - 340\*350\*70mm  
Weight - 1.2Kg



4 Reels in Anti-static Bags  
800 pcs in one carton  
Carton Dimensions - 370\*360\*305mm  
Weight - 5.6Kg



Pallet Dimensions 1200\*1000\*1420mm  
24 Cartons per Pallet  
6 Cartons per layer  
4 Layers



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